

PROCESS AND INSTALLATION FOR DOPING AN ETCHED PATTERN  
OF RESISTIVE ELEMENTS

Abstract of the Disclosure

A process for selectively doping predetermined resistive elements on an electronic chip is provided. The resistive elements are arranged in a pattern, and there are three phases in the process. The first phase electrically charges selected elements of the pattern. The second phase adds doping atoms to the charged elements as a function of their state of charge. The third phase anneals the electronic chip to cause penetration of the doping agents and to activate them.